

30V N-Channel SGT Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)TYP}$	I_D
30V	4.5mΩ @ $V_{GS}=10V$	60A
	6.3mΩ @ $V_{GS}=4.5V$	

Marking Information

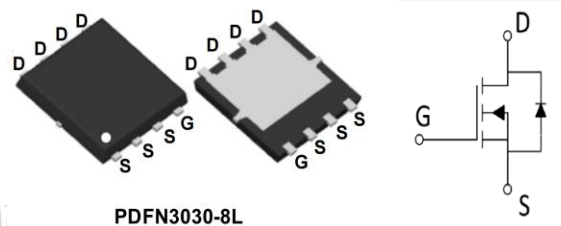
Device	Marking	Package	Shipping
LPM03N038GE	LPS M03N038GE YWX	PDFN3030-8L	5K/REEL
Marking indication: Y: Production year W: Production week X: Series Number			

Description

- SGT Power MOSFET Technology
- Low $R_{DS(ON)}$ and Low Gate Charge
- High Current Capability
- High Speed Switching
- 100% UIS Tested
- RoHS and Halogen-Free Compliant

Applications

- PWM Application
- Load Switch
- Power Management



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	60
		$T_C=100^\circ\text{C}$	36
Pulsed Drain Current ¹	I_{DM}	240	A
Single Pulse Avalanche Energy ²	E_{AS}	39	mJ
Total Power Dissipation ⁴	$T_C=25^\circ\text{C}$	P_D	35
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	46	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	3.5	$^\circ\text{C}/\text{W}$

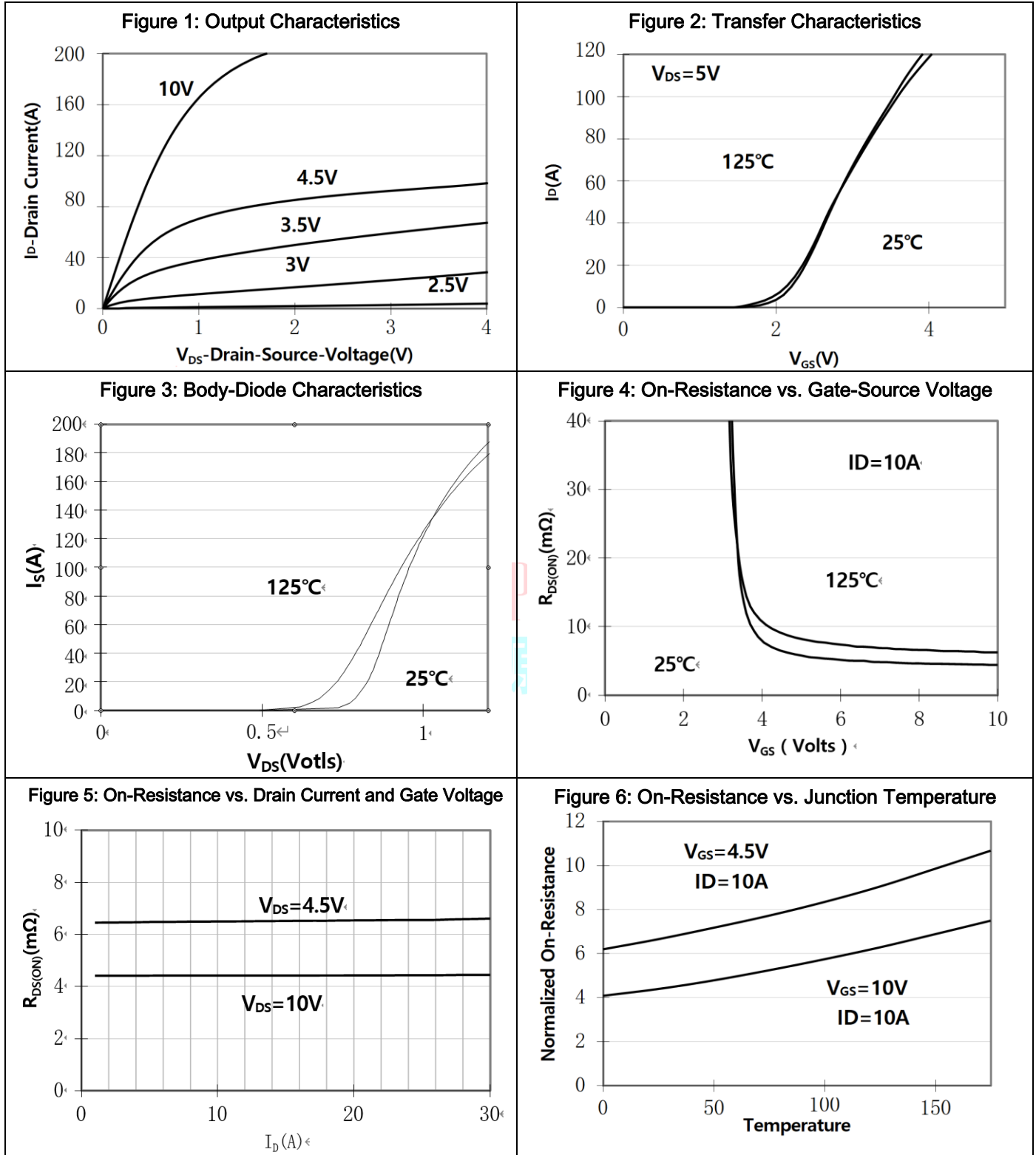
Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	30	-	-	V
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	T _J =25°C	-	1	μA
			T _J =100°C	-	100	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.1	1.5	1.9	V
Drain-Source on-Resistance ⁴	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	4.5	5.5	mΩ
		V _{GS} =4.5V, I _D =20A	-	6.3	7.9	mΩ
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz	-	753	-	pF
Output Capacitance	C _{oss}		-	331	-	pF
Reverse Transfer Capacitance	C _{rss}		-	30	-	pF
Gate Resistance	R _G	f=1MHz	-	1	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = 10V, V _{DS} =15V, I _D = 20A	-	13.5	-	nC
Gate-Source Charge	Q _{gs}		-	2.2	-	nC
Gate-Drain Charge	Q _{gd}		-	3.2	-	nC
Turn-on Delay Time	t _{d(on)}	V _{GS} =10V, V _{DD} =15V, R _G =3Ω, I _D =20A	-	4.5	-	nS
Rise Time	Tr		-	23	-	nS
Turn-off Delay Time	T _{d(off)}		-	14	-	nS
Fall Time	tf		-	6	-	nS
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S =1A, V _{GS} =0V	-	0.7	-	V
Continuous Source Current ^{1,5}	I _S	T _c =25°C	-	-	60	A

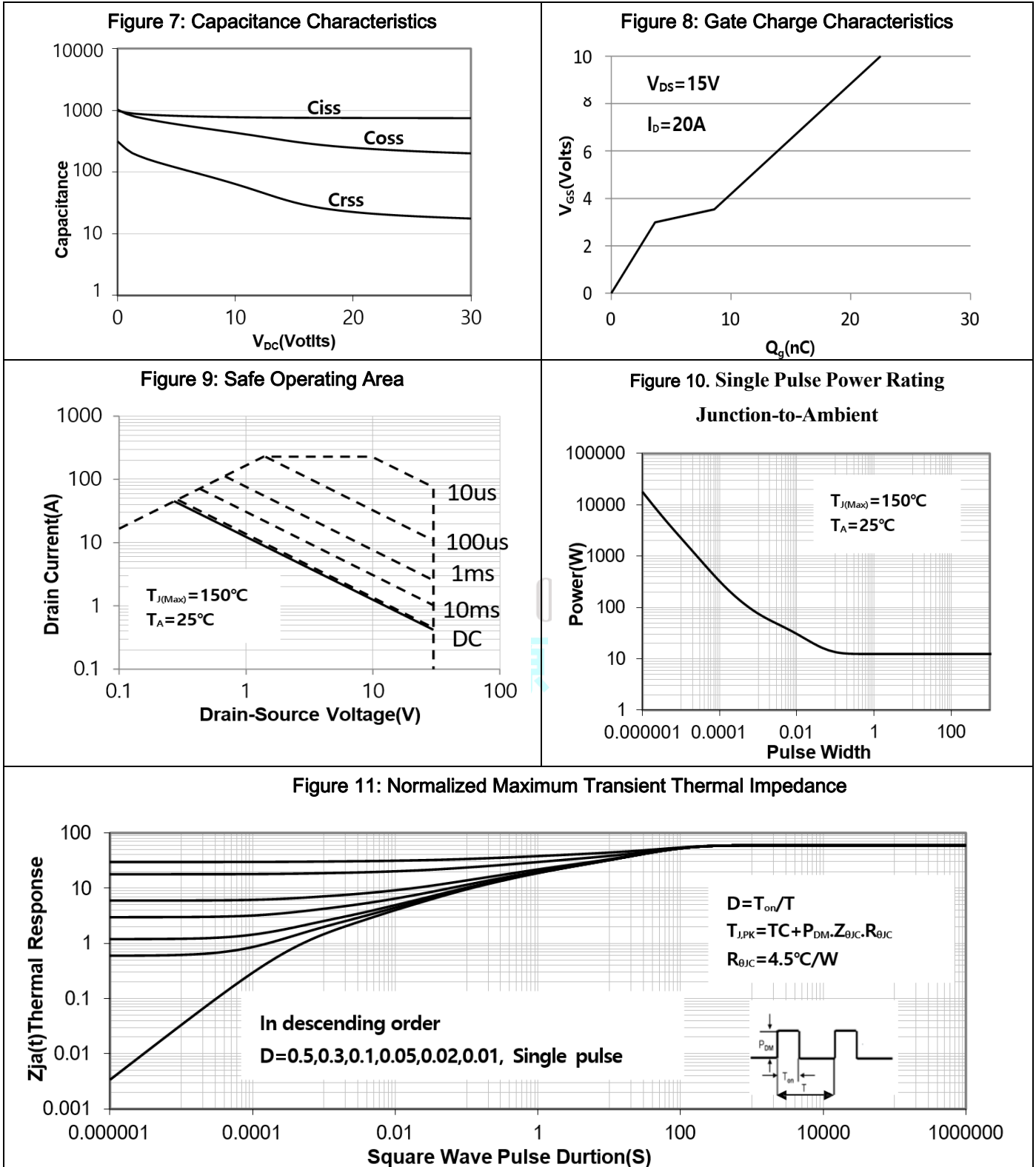
Notes:

1. Repetitive rating, pulse width limited by junction temperature T_J(MAX)=150°C.
2. The test condition is V_{DD}=24V, V_{GS}=10V, L=0.1mH
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics (Ta=25°C, unless otherwise noted)

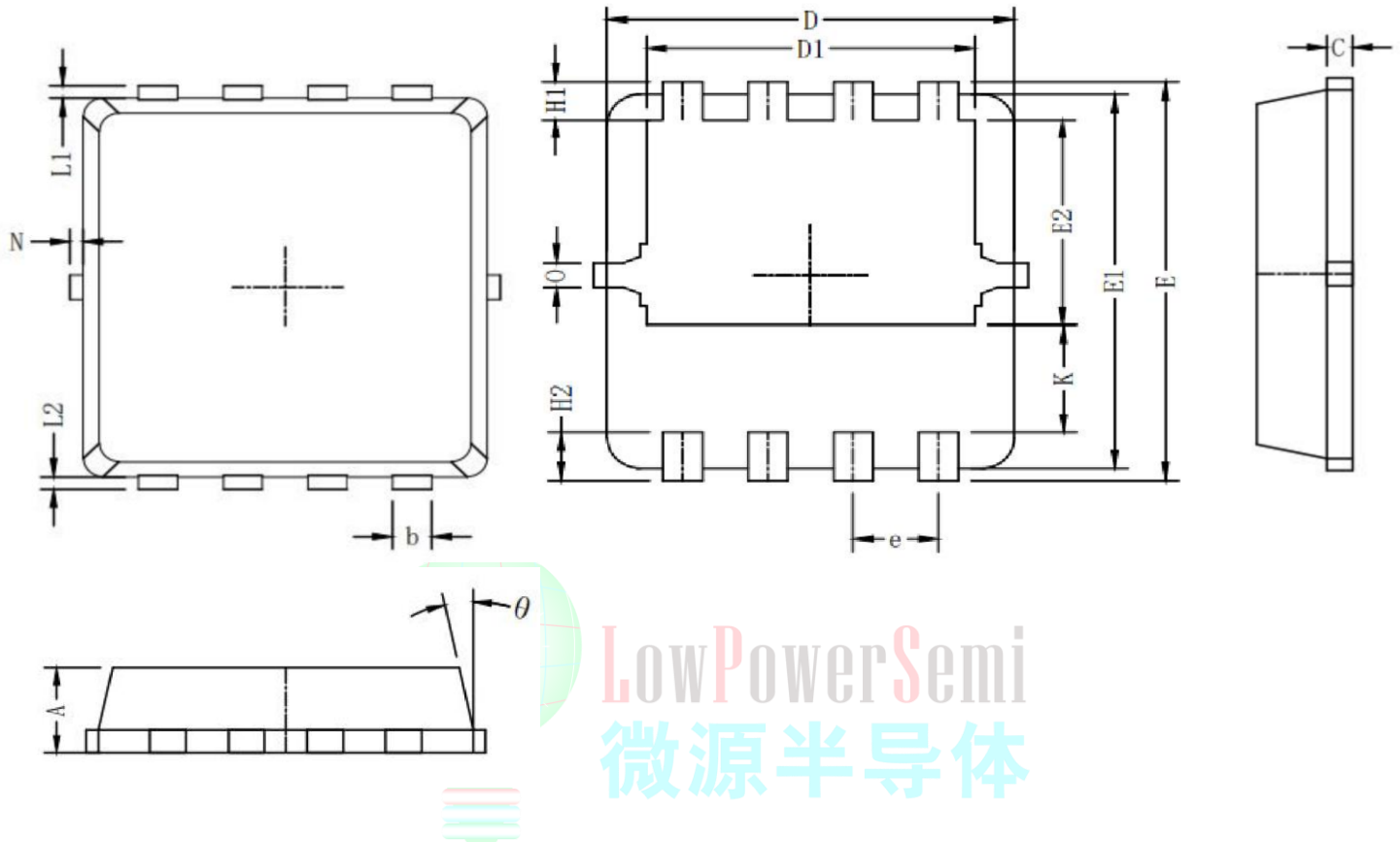


Typical Characteristics (Ta=25°C, unless otherwise noted)



Packaging Information:

Mechanical Dimensions for PDFN3030-8L



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.7	0.8	0.9
b	0.25	0.325	0.4
C	0.15	0.20	0.25
D	2.95	3.15	3.35
D1	2.3	2.5	2.7
E	3.1	3.3	3.5
E1	2.9	3.0	3.3
E2	1.60	1.82	2.0
e	0.65BSC		
H2	0.300	0.40	0.50
L1/L2	0.10	0.15	0.25
θ	11°	12°	13°